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CONFIRMATION NO. 3789

<b>SERIAL NUMBER</b> 10/653,907	<b>FILING OR 371(c) DATE</b> 09/04/2003 <b>RULE</b>	<b>CLASS</b> 714	<b>GROUP ART UNIT</b> 2818	<b>ATTORNEY DOCKET NO.</b> 500.41283VX1
<b>APPLICANTS</b> Youji Takahashi, Kudamatsu, JAPAN; Tsutomu Iida, Kudamatsu, JAPAN; Tsuyoshi Umemoto, Yamato, JAPAN; Makoto Kashibe, Tokuyama, JAPAN;				
<b>** CONTINUING DATA *****</b> This application is a DIV of 10/082,160 02/26/2002 PAT 6,713,885				
<b>** FOREIGN APPLICATIONS *****</b> None				
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> ** 11/25/2003				
Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after met Verified and Acknowledged <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance		<b>STATE OR COUNTRY</b> JAPAN	<b>SHEETS DRAWING</b> 6	<b>TOTAL CLAIMS</b> 3
<b>INDEPENDENT CLAIMS</b> 3				
<b>ADDRESS</b> 020457				
<b>TITLE</b> Power supply, a semiconductor making apparatus and a semiconductor wafer fabricating method using the same				
<b>FILING FEE RECEIVED</b> 750	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit	